

Title (en)  
ALUMINUM ALLOY

Title (de)  
ALUMINIUMLEGIERUNG

Title (fr)  
ALLIAGE D'ALUMINIUM

Publication  
**EP 1871555 A4 20100818 (EN)**

Application  
**EP 06739457 A 20060322**

Priority  
• US 2006010666 W 20060322  
• US 8508605 A 20050322

Abstract (en)  
[origin: US2005161128A1] All aluminum alloy is disclosed that includes 6.5 to 8.5 percent silicon, 0.6 to 1.0 percent iron, 0.3 to 0.5 percent manganese, 0.35 to 0.65 percent magnesium, 0.01 to 1.0 percent zinc, 0.11 to 0.2 percent titanium, 2.0 to 2.5 percent copper, and aluminum as the remainder with further one or more other elements that are 0.001 to 0.15 percent of the weight of the aluminum alloy. An aluminum alloy of the above composition is high in strength and suitable for use with SSM methods of casting, such as Rheocasting and Thixocasting.

IPC 8 full level  
**B22D 17/08** (2006.01); **B22D 17/00** (2006.01); **B22D 23/00** (2006.01); **B22D 25/00** (2006.01); **C22C 1/00** (2006.01); **C22C 21/02** (2006.01); **C22C 21/04** (2006.01)

CPC (source: EP US)  
**B22D 17/007** (2013.01 - EP US); **B22D 21/007** (2013.01 - EP US); **C22C 1/12** (2023.01 - EP US); **C22C 21/02** (2013.01 - EP US)

Citation (search report)  
• [X] WO 03080883 A1 20031002 - SPX CORP [US], et al  
• [A] DE 19524564 A1 19970102 - VAW ALUCAST GMBH [DE]  
• [A] EP 1340827 A1 20030903 - KS ALUMINIUM TECHNOLOGIE AG [DE], et al  
• [A] JP H11286758 A 19991019 - NIPPON LIGHT METAL CO  
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• [A] JP H06271966 A 19940927 - HONDA MOTOR CO LTD  
• [A] US 3480465 A 19691125 - IMABAYASHI MAMORU, et al  
• [A] WABUSSEG H ET AL: "THEORETISCHE GRUNDLAGEN UND PRAKTISCHE UMSETZUNG VON NEW RHEOCASTING FUER AL-LEGIERUNGEN", DRUCKGUSS-PRAxis, SCHIELE UND SCHOEN, DE, vol. 1, 1 January 2002 (2002-01-01), pages 16 - 19, XP008020455, ISSN: 1619-2478  
• See references of WO 2006102550A2

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DOCDB simple family (publication)  
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WO 2006102550 A3 20071108

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